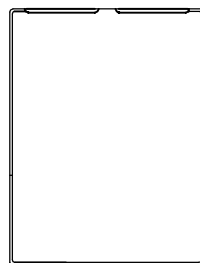
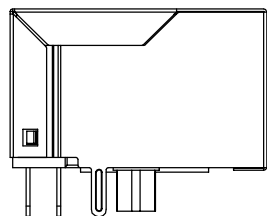


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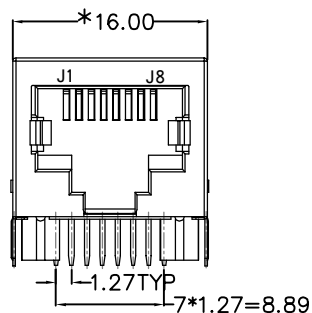
REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	ZG.Hu	2018.02.27



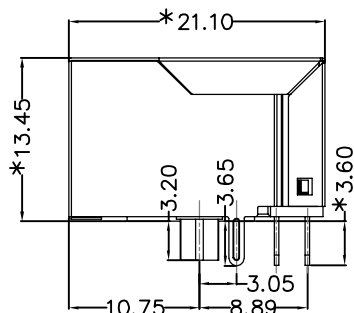
TOP VIEW



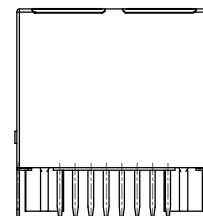
LEFT SIDE VIEW



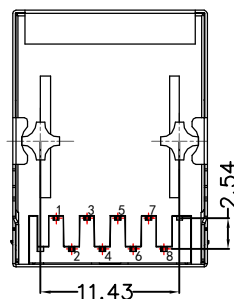
FRONT VIEW



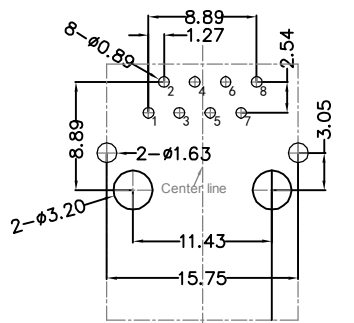
RIGHT SIDE VIEW



BACK VIEW



BOTTOM VIEW





RECOMMENDED PCB LAYOUT
VIEWED FROM COMPONENT SIDE

MATERIAL:

HOUSING: PBT,UL94V-0,BLACK.
TERMINALS BRACKET: PBT,UL94V-0,BLACK.
SHIELD: C2680,T=0.20MM,NICKEL PLATING ON ALL AREA.
TERMINAL: PHOSPHOR BRONZE C5210,T=0.35MM,
6U" GOLD PLATING ON CONTACT AREA.

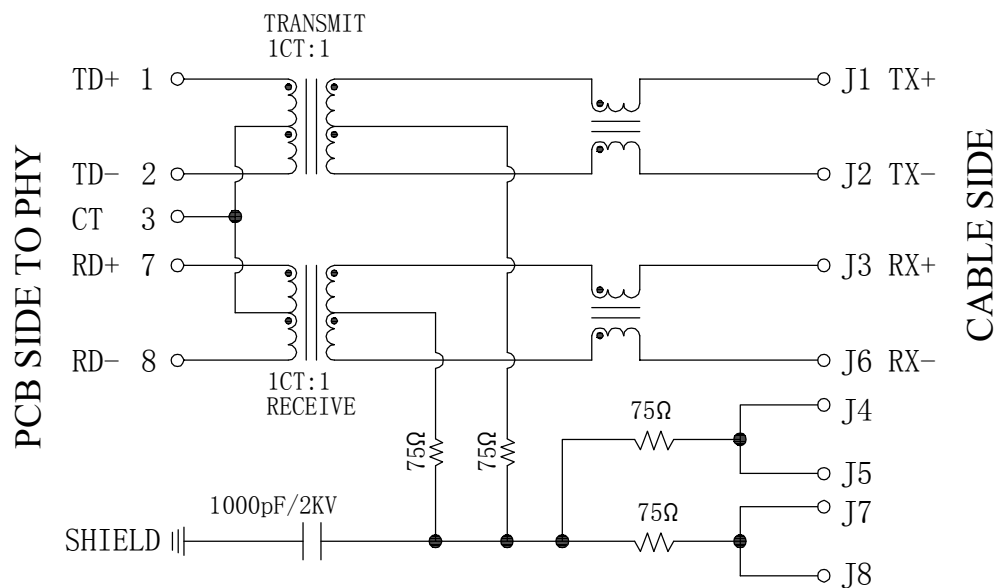
MECHANICAL:

DURABILITY: 750 CYCLES MIN.
MATING FORCE: 23N MAX.
OPERATING TEMPERATURE: -40°C~+85°C.
STORAGE TEMPERATURE: -40°C~+85°C.
ALL CRITICAL DIMENSIONS WITH "*"

 苏州沃虎电子科技有限公司 Su Zhou Wo Hu Electronic Tech.Co.,Ltd.	TITLE: TAB-DOWN 1X1 100BASE	SIZE A4	UNITS MM[INCH]	GENERAL TOLERANCES UNLESS SPECIFIED		APPROVED BY: JP.Gong
	PART NO.: SYT111B084GWA1D	SACLE 1:1	REV A0	x±0.35	x°±3.0°	CHECKED BY: TW.Xu
	REMARK:	SHEET 1/3		.xx±0.25	.xx°±1.5°	DESIGND BY: ZG.Hu
				.xxx±0.10	.xxx°±1.0°	


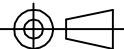
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A0	NEW	ZG.Hu	2018.02.27



Electrical:

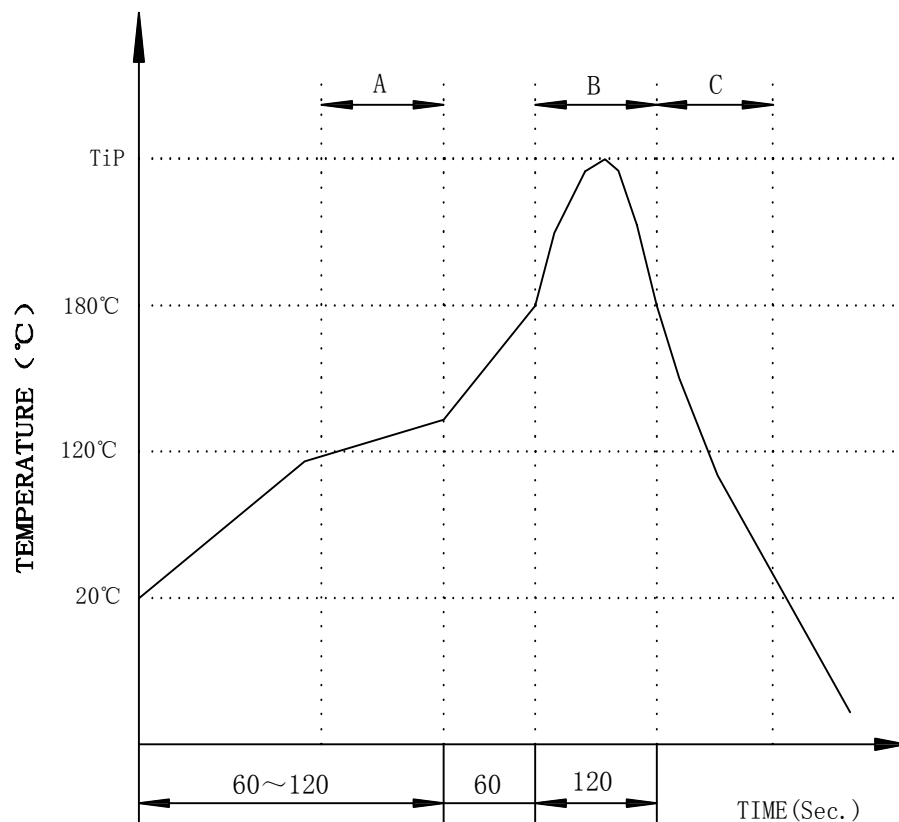
- Turn ratio: 1~2: J1~J2=1CT:1CT(±2%).
7~8: J3~J6=1CT:1CT(±2%).
- OCL: 350uH Min. at 100KHz 100mV 8mA DC.
- Insertion Loss: -1.0 dB Max 1~100MHz.
- Return loss: -20dB Min 1~10MHz;
-16dB Min 10~30MHz.
-12dB Min 30~60MHz.
-10dB Min 60~80MHz.
- Cross talk: -40dB Min 1~30MHz;
-35dB Min 30~60MHz;
-30dB Min 60~100MHz;
- CMR: -30dB Min 1~100MHz;
- Hi-Pot: 1500V AC & 2250V DC
6S 1mA PRI TO SEC

 苏州沃虎电子科技有限公司 Su Zhou Wo Hu Electronic Tech.Co.,Ltd.	TITLE: TAB-DOWN 1X1 100BASE	SIZE A4	UNITS MM[INCH]	GENERAL TOLERANCES UNLESS SPECIFIED		APPROVED BY: JP.Gong
	PART NO.: SYT111B084GWA1D	SACLE 1:1	REV A0	x±0.35	x°±3.0°	CHECKED BY: TW.Xu
	REMARK:	SHEET 2/3		.xx±0.25	.xx°±1.5°	DESIGND BY: ZG.Hu
				.xxx±0.10	.xxx°±1.0°	

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PROFILE OF WAVE SOLDER

REV.	ECN / DESCRIPTION	BY	DATE
A0	NEW	ZG.Hu	2018.02.27



A.Preheating B.Soldering C.Gradual Cooling
 Tip temperature:260±5°C.
 Tip temperature time:5Sec Max.
 Tip melting point of Sn96.5/Ag3/Cu0.5:217°C.

Remarks: after wave soldering, the plastic positioning columns of the product which under the PCB will be slightly melted, but it won't affect its function.

TITLE: TAB-DOWN 1X1 100BASE	SIZE A4	UNITS MM[INCH]	GENERAL TOLERANCES UNLESS SPECIFIED		APPROVED BY: JP.Gong
PART NO.: SYT111B084GWA1D	SACLE 1:1	REV A0	x±0.35	x°±3.0°	CHECKED BY: TW.Xu
REMARK:	SHEET 3/3		.xx±0.25	.xx°±1.5°	DESIGND BY: ZG.Hu
			.xxx±0.10	.xxx°±1.0°	

WOHU 苏州沃虎电子科技有限公司
Su Zhou Wo Hu Electronic Tech.Co.,Ltd.